

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3434898

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	CHENG-HAO YEH	09/04/2013
RECEIVING PARTY DATA		
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	
Street Address:	NO. 8, LI-HSIN ROAD 6	
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK	
City:	HSIN-CHU	
State/Country:	TAIWAN	
Postal Code:	300-77	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	14797212
CORRESPONDENCE DATA		
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ATTORNEY DOCKET NUMBER:	20100373US2/24061.2625US3	
NAME OF SUBMITTER:	ERIC Q. LI	
SIGNATURE:	/Eric Q. Li/	
DATE SIGNED:	07/13/2015	
Total Attachments: 2		
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Docket No.: 2010-0373-D / 24061.2625
Customer No.: 42717

ASSIGNMENT

WHEREAS, I

Chen-Hao Yeh of 10F-2, 168, Ta-tong Street, West Div.
Taichung City, Taiwan, R.O.C.

has invented certain improvements in

METAL LAYER END-CUT FLOW

for which I have executed an application for Letters Patent of the United States of America,

_____ of even date filed herewith; and
_____ filed on _____ and assigned application number _____; and

WHEREAS, I authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

AND I HEREBY further covenant and agree that I will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

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Inventor Name: Chen-Hao Yeh

Residence Address: 10F-2, 168, Ta-tong Street, West Div.
Taichung City, Taiwan, R.O.C.

Dated: 2013/09/04


Inventor Signature
